

January 1992 Revised August 2000

#### 100397

## **Quad Differential ECL/TTL Translating Transceiver** with Latch

#### **General Description**

The 100397 is a quad latched transceiver designed to convert TTL logic levels to differential F100K ECL logic levels and vice versa. This device was designed with the capability of driving a differential 25 $\Omega$  ECL load with cutoff capability, and will sink a 64 mA TTL load. The 100397 is ideal for mixed technology applications utilizing either an ECL or TTL backplane.

The direction of translation is set by the direction control pin (DIR). The DIR pin on the 100397 accepts F100K ECL logic levels. An ECL LOW on DIR sets up the ECL pins as inputs and TTL pins as outputs. An ECL HIGH on DIR sets up the TTL pins as inputs and ECL pins as outputs.

A LOW on the output enable input pin (OE) holds the ECL output in a cut-off state and the TTL outputs at a high impedance level. A HIGH on the latch enable input (LE) latches the data at both inputs even though only one output is enabled at the time. A LOW on LE makes the latch transparent.

The cut-off state is designed to be more negative than a normal ECL LOW level. This allows the output emitterfollowers to turn off when the termination supply is –2.0V, presenting a high impedance to the data bus. This high impedance reduces termination power and prevents loss of low state noise margin when several loads share the bus.

The 100397 is designed with FAST® TTL output buffers, featuring optimal DC drive and capable of quickly charging and discharging highly capacitive loads. All inputs have 50 K $\Omega$  pull-down resistors.

#### **Features**

- Differential ECL input/output structure
- 64 mA FAST TTL outputs
- $\blacksquare$  25 $\Omega$  differential ECL outputs with cut-off
- Bi-directional translation
- 2000V ESD protection
- Latched outputs
- 3-STATE outputs
- Voltage compensated operating range = -4.2V to -5.7V

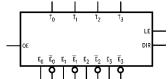
#### **Ordering Code:**

Order Number	Package Number	Package Description
100397PC	N24E	24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-010, 0.400 Wide
100397QC	V28A	28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square
100397QI		28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square Industrial Temperature Range (-40°C to +85°C)

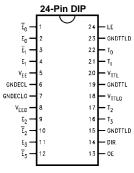
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

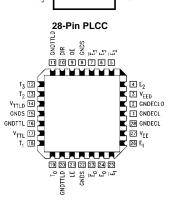
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### **Logic Symbol**



#### **Connection Diagrams**





#### **Pin Descriptions**

Pin Names	Description
E <sub>0</sub> –E <sub>3</sub>	ECL Data I/O
$\overline{E}_0 - \overline{E}_3$	Complementary ECL Data I/O
T <sub>0</sub> -T <sub>3</sub>	TTL Data I/O
OE	Output Enable Input (ECL Levels)
LE	Latch Enable Input (ECL Levels)
DIR	Direction Control Input (ECL levels)
GNDECL	ECL Ground
GNDECLO	ECL Output Ground
GNDS	ECL Ground-to-Substrate
V <sub>EE</sub>	ECL Quiescent Power Supply
$V_{EED}$	ECL Dynamic Power Supply
GNDTTL	TTL Quiescent Ground
GNDTTLD	TTL Dynamic Ground
$V_{TTL}$	TTL Quiescent Power Supply
$V_{TTLD}$	TTL Dynamic Power Supply

All pins function at 100K ECL levels except for T<sub>0</sub>-T<sub>3</sub>.

#### **Truth Table**

LE	DIR	OE	ECL	TTL	Notes
LE	DIK	OE	Port	Port	Notes
0	0	0	LOW	Z	
			(Cut-Off)		
0	0	1	Input	Output	(Note 1)(Note 4)
0	1	0	LOW	Z	
			(Cut-Off)		
0	1	1	Output	Input	(Note 2)(Note 4)
1	0	0	Input	Z	(Note 1)(Note 3)
1	0	1	Latched	Х	(Note 1)(Note 3)
1	1	0	LOW	Input	(Note 2)(Note 3)
			(Cut-Off)		
1	1	1	Latched	Х	(Note 2)(Note 3)

H = HIGH Voltage Level

L = LOW Voltage Level X = Don't Care

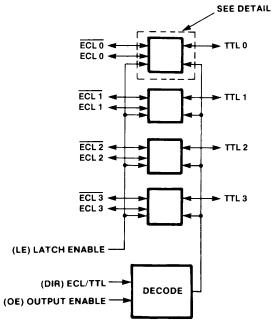
Z = High Impedance

Note 1: ECL input to TTL output mode. Note 2: TTL input to ECL output mode.

Note 3: Retains data present before LE set HIGH.

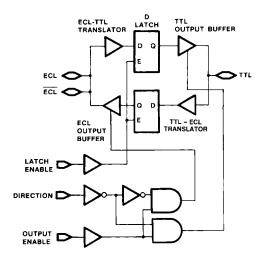
Note 4: Latch is transparent.

#### **Functional Diagram**



Note: LE, DIR, and OE use ECL logic levels

#### Detail



#### **Absolute Maximum Ratings**(Note 5)

-65°C to +150°C

Storage Temperature (T<sub>STG</sub>) Maximum Junction Temperature

+150°C

V<sub>EE</sub> Pin Potential to Ground Pin -7.0V to +0.5VV<sub>TTL</sub> Pin Potential to Ground Pin -0.5V to +6.0VECL Input Voltage (DC)  $V_{\text{EE}}$  to +0.5V

**ECL Output Current** 

(DC Output HIGH) -50 mA TTL Input Voltage (Note 7) -0.5V to +7.0V $-30\ mA$  to  $+5.0\ mA$ 

TTL Input Current (Note 7) Voltage Applied to Output

in HIGH State

-0.5V to +5.5V 3-STATE Output

Current Applied to TTL

Output in LOW State (Max) twice the Rated I<sub>OL</sub> (mA)

ESD (Note 6)

#### **Recommended Operating Conditions**

Case Temperature (T<sub>C</sub>)

Commercial 0°C to +85°C -40°C to +85°C Industrial -5.7V to -4.2V ECL Supply Voltage (V<sub>EE</sub>) TTL Supply Voltage (V<sub>TTL</sub>) +4.5V to +5.5V

Note 5: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum rating. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 6: ESD testing conforms to MIL-STD-883, Method 3015. Note 7: Either voltage limit or current limit is sufficient to protect inputs.

#### **Commercial Version**

#### TTL-to-ECL DC Electrical Characteristics (Note 8)

 $V_{EE} = -4.2V$  to -5.7V. GND = 0V.  $T_{C} = 0^{\circ}$ C to  $+85^{\circ}$ C.  $V_{TT1} = +4.5V$  to +5.5V

Symbol	Parameter	Min	Тур	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	-1025	-955	-870	mV	$V_{IN} = V_{IH(Max)}$ or $V_{IL(Min)}$
V <sub>OL</sub>	Output LOW Voltage	-1830	-1705	-1620	mV	Loading with 50Ω to – 2V
	Cutoff Voltage					OE and LE Low, DIR High
			-2000	-1950	mV	$V_{IN} = V_{IH(Max)}$ or $V_{IL}(Min)$ ,
						Loading with $50\Omega$ to $-2V$
V <sub>OHC</sub>	Output HIGH Voltage	-1035			mV	
	Corner Point High	-1035			mv	$V_{IN} = V_{IH(Min)}$ or $V_{IL(Max)}$
V <sub>OLC</sub>	Output LOW Voltage			-1610	mV	Loading with 50Ω to -2V
	Corner Point Low			-1010	IIIV	
V <sub>IH</sub>	Input HIGH Voltage	2.0		5.0	V	Over V <sub>TTL</sub> , V <sub>EE</sub> , T <sub>C</sub> Range
V <sub>IL</sub>	Input LOW Voltage	0		0.8	V	Over V <sub>TTL</sub> , V <sub>EE</sub> , T <sub>C</sub> Range
I <sub>IH</sub>	Input HIGH Current			5.0	μΑ	$V_{IN} = +2.7V$
I <sub>BVIT</sub>	Input HIGH Current			0.5	mA	V <sub>IN</sub> = 5.5V
	Breakdown (I/O)			0.5	IIIA	V <sub>IN</sub> = 5.5V
I <sub>IL</sub>	Input LOW Current	-1.0			mA	$V_{IN} = +0.5V$
V <sub>FCD</sub>	Input Clamp	-1.2			V	I <sub>IN</sub> = -18 mA
	Diode Voltage	-1.2			v	IIN = -10 IIIA
I <sub>EE</sub>	V <sub>EE</sub> Supply Current	-99		-50		LE Low, OE and DIR HIGH
						Inputs Open
I <sub>EEZ</sub>	V <sub>EE</sub> Supply Current	-159		-90		LE and OE Low, Dir HIGH
						Inputs Open

Note 8: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

#### Commercial Version (Continued)

#### **ECL-to-TTL DC Electrical Characteristics** (Note 9)

Symbol	Parameter	Min	Тур	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	2.7	3.1		V	$I_{OH} = -3 \text{ mA}, V_{TTL} = 4.75 \text{V}$
		2.4	2.9		V	$I_{OH} = -3 \text{ mA}, V_{TTL} = 4.50 \text{V}$
V <sub>OL</sub>	Output LOW Voltage		0.3	0.5	V	I <sub>OL</sub> = 24 mA, V <sub>TTL</sub> = 4.50V
V <sub>IH</sub>	Input HIGH Voltage	-1165		-870	mV	Guaranteed HIGH Signal for All Inputs
V <sub>IL</sub>	Input LOW Voltage	-1830		-1475	mV	Guaranteed LOW Signal for All Inputs
$V_{DIFF}$	Input Voltage Differential	150			mV	Required for Full Output Swing
V <sub>CM</sub>	Common Mode Voltage	GNDECL - 2.0		GNDECL - 0.5	V	
I <sub>IH</sub>	Input HIGH Current					
	$E_0-E_3$ , $\overline{E}_0-\overline{E}_3$			240	μΑ	$V_{IN} = V_{IH(Max)}$
	OE, LE, DIR			35		
I <sub>CEX</sub>	Output HIGH			50	μА	$V_{OUT} = V_{TTL}$
	Leakage Current			50	μА	VOUT = VTTL
I <sub>ZZ</sub>	Bus Drainage Test			500	μΑ	V <sub>OUT</sub> = 5.25V
						$V_{TTL} = 0.0V$
I <sub>IL</sub>	Input LOW Current	0.50			μΑ	$V_{IN} = V_{IL(Min)}$
I <sub>OZHT</sub>	3-STATE Current			70	μА	V <sub>OLIT</sub> = +2.7V
	Output High			70	μΛ	VOUT - +2.7 V
I <sub>OZLT</sub>	3-STATE Current	-650			μА	V <sub>OLIT</sub> = +0.5V
	Output Low	-030			μΛ	VOUT - +0.5 V
Ios	Output Short-Circuit	-100		-225	mA	$V_{OLIT} = 0.0V, V_{TTL} = +5.5V$
	Current	-100		-223	ША	VOUT = 0.0 V, VTTL = +3.3 V
I <sub>TTL</sub>	V <sub>TTL</sub> Supply Current			39	mA	TTL Outputs LOW
				27	mA	TTL Outputs HIGH
				39	mA	TTL Outputs in 3-STATE

Note 9: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

#### **DIP and PCC TTL-to-ECL AC Electrical Characteristics**

 $\ensuremath{\text{V}_{\text{EE}}} = -4.2\ensuremath{\text{V}}$  to  $-5.7\ensuremath{\text{V}},\ensuremath{\ensuremath{\text{V}_{\text{TTL}}}} = +4.5\ensuremath{\ensuremath{\text{V}}}$  to  $+5.5\ensuremath{\text{V}}$ 

Symbol	Parameter	$T_C = 0^{\circ}C$		T <sub>C</sub> = 25°C		T <sub>C</sub> = 85°C		Units	Conditions
Зупівої	Farameter	Min	Max	Min	Max	Min	Max	Units	Conditions
f <sub>MAX</sub>	Maximum Clock Frequency	180		180		180		MHz	
t <sub>PLH</sub> t <sub>PHL</sub>	$T_n$ to $E_n$ , $\overline{E}_n$ (Transparent)	0.9	2.1	0.8	2.2	0.7	2.5	ns	Figures 1, 3
t <sub>PLH</sub> t <sub>PHL</sub>	LE to E <sub>n</sub> , Ē <sub>n</sub>	1.2	2.3	1.3	2.4	1.4	2.5	ns	Figures 1, 3
t <sub>PZH</sub>	OE to $E_n$ , $\overline{E}_n$ (Cutoff to HIGH)	2.5	4.5	2.5	4.5	2.5	4.6	ns	Figures 1, 3
t <sub>PHZ</sub>	OE to $E_n$ , $\overline{E}_n$ (HIGH to Cutoff)	2.1	3.8	2.3	4.0	2.5	4.5	ns	Figures 1, 3
t <sub>PHZ</sub>	DIR to $E_n$ , $\overline{E}_n$ (HIGH to Cutoff)	2.0	3.5	2.1	3.7	2.3	4.2	ns	Figures 1, 3
t <sub>S</sub>	T <sub>n</sub> to LE	0.8		0.8		0.8		ns	Figures 1, 3
t <sub>H</sub>	T <sub>n</sub> to LE	0.6		0.6		0.6		ns	Figures 1, 3
t <sub>TLH</sub> t <sub>THL</sub>	Transition Time 20% to 80%, 80% to 20%	0.8	2.8	0.8	2.8	0.8	2.8	ns	Figures 1, 3

## Commercial Version (Continued) DIP and PCC ECL-to-TTL AC Electrical Characteristics

 $V_{\text{EE}} = -4.2 \text{V to } -5.7 \text{V}, \ V_{\text{TTL}} = +4.5 \text{V to } +5.5 \text{V}, \ C_{\text{L}} = 50 \ \text{pF}$ 

Symbol	Parameter	T <sub>C</sub> =	= 0°C	T <sub>C</sub> =	25°C	T <sub>C</sub> =	85°C	Units	Conditions
Oymboi	T didilicter	Min	Max	Min	Max	Min	Max	Oiiita	
f <sub>MAX</sub>	Maximum Clock Frequency	75		75		75		MHz	
t <sub>PLH</sub> t <sub>PHL</sub>	$E_n$ , $\overline{E}_n$ to $T_n$ (Transparent)	1.7	4.9	1.7	5.1	1.8	5.8	ns	Figures 2, 4
t <sub>PLH</sub>	LE to T <sub>n</sub>	2.2	4.0	2.2	4.0	2.3	4.1	ns	Figures 2, 4
t <sub>PHL</sub>		3.3	5.2	3.4	5.4	3.8	6.1	113	1 iguies 2, 4
t <sub>PZH</sub>	OE to T <sub>n</sub>	3.2	5.6	3.3	5.7	3.6	6.3	ns	Figures 2, 5
t <sub>PZL</sub>	(Enable Time)	4.9	8.3	5.1	8.5	5.6	9.2		1 194100 2, 0
t <sub>PHZ</sub>	OE to T <sub>n</sub>	3.6	8.6	3.5	8.3	3.5	7.5	ns	Figures 2, 5
t <sub>PLZ</sub>	(Disable Time)	3.4	6.9	3.5	6.7	3.6	6.7	115	rigules 2, 5
t <sub>PHZ</sub>	DIR to T <sub>n</sub>	3.5	8.1	3.5	8.1	3.5	7.6	ns	Figures 2, 6
$t_{PLZ}$	(Disable Time)	3.4	6.8	3.4	6.7	3.6	6.7	115	rigules 2, 0
t <sub>S</sub>	$E_n$ , $\overline{E}_n$ to LE	0.6		0.6		0.6		ns	Figures 2, 4
t <sub>H</sub>	$E_n$ , $\overline{E}_n$ to LE	0.7		0.7		0.7		ns	Figures 2, 4
t <sub>PW</sub> (L)	Pulse Width LE	2.0		2.0		2.0		ns	Figures 2, 4

#### **Industrial Version**

#### TTL-to-ECL DC Electrical Characteristics (Note 10)

 $V_{EE} = -4.2 V$  to -5.7 V, GND = 0V,  $T_C = -40 ^{\circ} C$  to  $+85 ^{\circ} C$ ,  $V_{TTL} = +4.5 V$  to +5.5 V

Symbol	Parameter	Min	Тур	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	-1085	-955	-870	mV	$V_{IN} = V_{IH(Max)}$ or $V_{IL(Min)}$
V <sub>OL</sub>	Output LOW Voltage	-1830	-1705	-1575	mV	Loading with 50Ω to -2V
	Cutoff Voltage					OE and LE LOW, DIR HIGH
			-2000	-1900	mV	$V_{IN} = V_{IH(Max)}$ or $V_{IL(Min)}$ ,
						Loading with 50Ω to –2V
V <sub>OHC</sub>	Output HIGH Voltage	-1095			mV	
	Corner Point HIGH	-1033			1117	$V_{IN} = V_{IH(Min)}$ or $V_{IL(Max)}$
V <sub>OLC</sub>	Output LOW Voltage			-1565	mV	Loading with 50Ω to -2V
	Corner Point LOW			-1303	IIIV	
V <sub>IH</sub>	Input HIGH Voltage	2.0		5.0	V	Over V <sub>TTL</sub> , V <sub>EE</sub> , T <sub>C</sub> Range
V <sub>IL</sub>	Input LOW Voltage	0		0.8	V	Over V <sub>TTL</sub> , V <sub>EE</sub> , T <sub>C</sub> Range
I <sub>IH</sub>	Input HIGH Current			5.0	μΑ	V <sub>IN</sub> = +2.7V
I <sub>BVIT</sub>	Input HIGH Current			0.5	mA	V <sub>IN</sub> = 5.5V
	Breakdown (I/O)			0.5	IIIA	VIN - 3.3V
I <sub>IL</sub>	Input LOW Current	-1.0			mA	V <sub>IN</sub> = +0.5V
V <sub>FCD</sub>	Input Clamp	-1.2			V	I <sub>IN</sub> = -18 mA
	Diode Voltage	-1.2			V	IIN 10 IIIA
I <sub>EE</sub>	V <sub>EE</sub> Supply Current	-99		-40		LE Low, OE and DIR HIGH
						Inputs Open
I <sub>EEZ</sub>	V <sub>EE</sub> Supply Current	-159		-90		LE and OE LOW, Dir HIGH
						Inputs Open

Note 10: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

#### Industrial Version (Continued)

#### **ECL-to-TTL DC Electrical Characteristics** (Note 11)

 $V_{EE} = -4.2V$  to -5.7V, GND = 0V,  $T_{C} = -40^{\circ}$ C to  $+85^{\circ}$ C,  $C_{L} = 50$  pF,  $V_{TTL} = +4.5V$  to +5.5V

Symbol	Parameter	Min	Тур	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	2.7	3.1		V	$I_{OH} = -3 \text{ mA}, V_{TTL} = 4.75 \text{V}$
		2.4	2.9		V	$I_{OH} = -3 \text{ mA}, V_{TTL} = 4.50 \text{V}$
V <sub>OL</sub>	Output LOW Voltage		0.3	0.5	V	I <sub>OL</sub> = 24 mA, V <sub>TTL</sub> = 4.50V
V <sub>IH</sub>	Input HIGH Voltage	-1170		-870	mV	Guaranteed HIGH Signal for All Inputs
V <sub>IL</sub>	Input LOW Voltage	-1830		-1480	mV	Guaranteed LOW Signal for All Inputs
$V_{DIFF}$	Input Voltage Differential	150			mV	Required for Full Output Swing
V <sub>CM</sub>	Common Mode Voltage	GNDECL - 2.0		GNDECL - 0.5	V	
I <sub>IH</sub>	Input HIGH Current					$V_{IN} = V_{IH(Max)}$
	$E_0-E_3$ , $\overline{E}_0-\overline{E}_3$			300	μΑ	
	OE, LE, DIR			35		
I <sub>CEX</sub>	Output HIGH			50	^	V V
	Leakage Current			50	μΑ	$V_{OUT} = V_{TTL}$
I <sub>ZZ</sub>	Bus Drainage Test			500	μΑ	V <sub>OUT</sub> = 5.25V
						V <sub>TTL</sub> = 0.0V
I <sub>IL</sub>	Input LOW Current	0.50			μΑ	$V_{IN} = V_{IL(Min)}$
I <sub>OZHT</sub>	3-STATE Current			70	μА	V <sub>OLIT</sub> = +2.7V
	Output HIGH			70	μΛ	VOUT - +2.7 V
I <sub>OZLT</sub>	3-STATE Current	-650			μА	V <sub>OUT</sub> = +0.5V
	Output LOW	-650			μА	
Ios	Output Short-Circuit Current	-100		-225	mA	$V_{OUT} = 0.0V, V_{TTL} = +5.5V$
I <sub>TTL</sub>	V <sub>TTL</sub> Supply Current			39	mA	TTL Outputs LOW
				27	mA	TTL Outputs HIGH
				39	mA	TTL Outputs in 3-STATE

Note 11: The specified limits represent the "worst case" value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guardbanding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under "worst case" conditions.

#### **PCC TTL-to-ECL AC Electrical Characteristics**

 $V_{\mbox{\footnotesize EE}} = -4.2 \mbox{\footnotesize V}$  to  $-5.7 \mbox{\footnotesize V}, \mbox{\footnotesize $V_{\mbox{\footnotesize TTL}}$} = +4.5 \mbox{\footnotesize V}$  to  $+5.5 \mbox{\footnotesize V}$ 

Symbol	Parameter	T <sub>C</sub> =	$T_C = -40^{\circ}C$		$T_C = +25^{\circ}C$		$T_C = +85^{\circ}C$		Conditions
Зупівої		Min	Max	Min	Max	Min	Max	Units	Conditions
f <sub>MAX</sub>	Maximum Clock Frequency	180		180		180		MHz	
t <sub>PLH</sub>	$T_n$ to $E_n$ , $\overline{E}_n$ (Transparent)	0.9	2.4	0.8	2.2	0.7	2.5	ns	Figures 1, 3
t <sub>PLH</sub> t <sub>PHL</sub>	LE to $E_n$ , $\overline{E}_n$	1.2	2.3	1.3	2.4	1.4	2.5	ns	Figures 1, 3
t <sub>PZH</sub>	OE to $E_n$ , $\overline{E}_n$ (Cutoff to HIGH)	1.9	3.8	2.5	4.5	2.5	4.6	ns	Figures 1, 3
t <sub>PHZ</sub>	OE to $E_n$ , $\overline{E}_n$ (HIGH to Cutoff)	2.5	4.7	2.3	4.0	2.5	4.5	ns	Figures 1, 3
t <sub>PHZ</sub>	DIR to $E_n$ , $\overline{E}_n$ (HIGH to Cutoff)	1.8	3.5	2.1	3.7	2.3	4.2	ns	Figures 1, 3
t <sub>S</sub>	T <sub>n</sub> to LE	0.8		0.8		8.0		ns	Figures 1, 3
t <sub>H</sub>	T <sub>n</sub> to LE	0.6		0.6		0.6		ns	Figures 1, 3
t <sub>TLH</sub> t <sub>THL</sub>	Transition Time 20% to 80%, 80% to 20%	0.8	2.8	0.8	2.8	0.8	2.8	ns	Figures 1, 3

# Industrial Version (Continued) PCC ECL-to-TTL AC Electrical Characteristics V<sub>EE</sub> = -4.2V to -5.7V, V<sub>TTL</sub> = +4.5V to +5.5V, C<sub>L</sub> = 50 pF

Symbol	Parameter	T <sub>C</sub> =	–40°C	$T_C = +25^{\circ}C$		T <sub>C</sub> = +85°C		Units	Conditions
Symbol	i arameter	Min	Max	Min	Max	Min	Max	Units	Conditions
f <sub>MAX</sub>	Maximum Clock Frequency	75		75		75		MHz	
t <sub>PLH</sub> t <sub>PHL</sub>	$E_n$ , $\overline{E}_n$ to $T_n$ (Transparent)	1.7	4.9	1.7	5.1	1.8	5.8	ns	Figures 2, 4
t <sub>PLH</sub> t <sub>PHL</sub>	LE to T <sub>n</sub>	2.2 3.3	4.3 5.2	2.2 3.4	4.0 5.4	2.3 3.8	4.1 6.1	ns	Figures 2, 4
t <sub>PZH</sub>	OE to T <sub>n</sub> (Enable Time)	3.1 4.8	5.6 8.3	3.3 5.1	5.7 8.5	3.6 5.6	6.3 9.2	ns	Figures 2, 5
t <sub>PHZ</sub> t <sub>PLZ</sub>	OE to T <sub>n</sub> (Disable Time)	3.5 3.2	9.2 7.3	3.5 3.5	8.3 6.7	3.5 3.6	7.5 6.7	ns	Figures 2, 5
t <sub>PHZ</sub> t <sub>PLZ</sub>	DIR to T <sub>n</sub> (Disable Time)	3.5 3.2	8.8 7.2	3.5 3.4	8.1 6.7	3.5 3.6	7.6 6.7	ns	Figures 2, 6
t <sub>S</sub>	$E_n$ , $\overline{E}_n$ to LE	0.6		0.6		0.6		ns	Figures 2, 4
t <sub>H</sub>	$E_n$ , $\overline{E}_n$ to LE	0.7		0.7		0.7		ns	Figures 2, 4
t <sub>PW</sub> (L)	Pulse Width LE	2.0		2.0		2.0		ns	Figures 2, 4

#### **Test Circuitry (TTL-to-ECL)** $V_{TTL} = 5V$ GND = OV ECL OUTPUT SENSE CIRCUIT TTL INPUT FORCE/SENSE CIRCUIT 50Ω COAX E (OUT) **4**50Ω 2:1 DIVIDER 100Ω DIR OE EQUIVALENT CIRCUIT FOR $-2V/50\Omega$ TERMINATION TTL INPUT SENSE -0.95V 10:1 DIVIDER CIRCUIT = $500\Omega$ TO GROUND ECL INPUT FORCE/SENSE CIRCUIT -0.95V $F_{\text{ECL}}$ ■ ECL INPUT FORCE/SENSE CIRCUIT 2:1 DIVIDER 100Ω EQUIVALENT CIRCUIT FOR -2V/50Ω TERMINATION

#### Notes:

 $R_t = 50\Omega$  termination. When an input or output is being monitored by a scope,  $R_t$  is supplied by the scope's  $50\Omega$  resistance. When an input or output is not being monitored, and external  $50\Omega$  resistance must be applied to serve as R<sub>t</sub>.

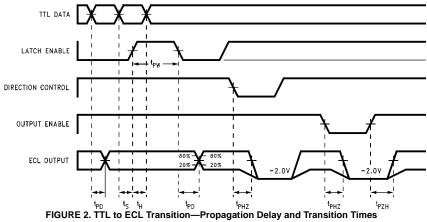
TTL and ECL force signals are brought to the DUT via  $50\Omega$  coax lines.

 $V_{TTL} \text{ is decoupled to ground with 0.1} \ \mu\text{F to ground, } V_{EE} \text{ is decoupled to ground with 0.01} \ \mu\text{F and GND is connected to ground.}$ 

For ECL input pins, the equivalent force/sense circuitry is optional.

#### FIGURE 1. TTL-to-ECL AC Test Circuit

#### **Switching Waveforms (TTL-to-ECL)**



#### **Test Circuitry (ECL-to-TTL)** $V_{TTL} = 5V$ GND = OV ECL INPUT FORCE/SENSE CIRCUIT $F_{ECL}$ TTL OUTPUT SENSE CIRCUIT 50Ω COAX LZ/ZL 3-STATE PULL-UP 50Ω 500Ω E (IN 450Ω 2:1 DIVIDER 100Ω DIR OF EQUIVALENT CIRCUIT FOR $-2V/50\Omega$ TERMINATION 50 pF 50Ω 10:1 DIVIDER ECL INPUT FORCE/SENSE CIRCUIT -0.95V $F_{\text{ECL}}$ ■ ECL INPUT FORCE/SENSE CIRCUIT 2:1 DIVIDER 100Ω EQUIVALENT CIRCUIT FOR $-2V/50\,\Omega$ TERMINATION

#### Notes:

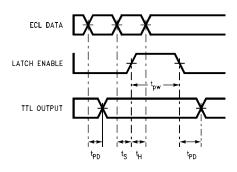
 $R_t = 50\Omega$  termination. When an input or output is being monitored by a scope,  $R_t$  is supplied by the scope's  $50\Omega$  resistance. When an input or output is not being monitored, and external  $50\Omega$  resistance must be applied to serve as  $R_t$ .

The TTL 3-STATE pull up switch is connected to +7V only for ZL and LZ tests.

TTL and ECL force signals are brought to the DUT via  $50\Omega$  coax lines.

 $V_{TTL} \text{ is decoupled to ground with 0.1} \ \mu\text{F to ground, } V_{EE} \text{ is decoupled to ground with 0.01} \ \mu\text{F and GND is connected to ground.}$ 

#### FIGURE 3. ECL-to-TTL AC Test Circuit



#### Note:

DIR is LOW, and OE is HIGH

FIGURE 4. ECL-to-TTL Transition—Propagation Delay and Transition Times

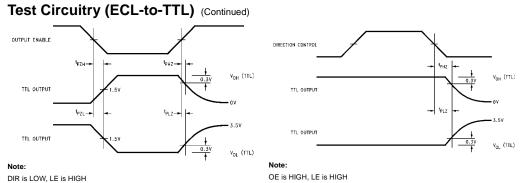


FIGURE 5. ECL-to-TTL Transition, OE to TTL Output, Enable and Disable Times

FIGURE 6. ECL-to-TTL Transition, DIR to TTL Output, Disable Time

#### **Applications**

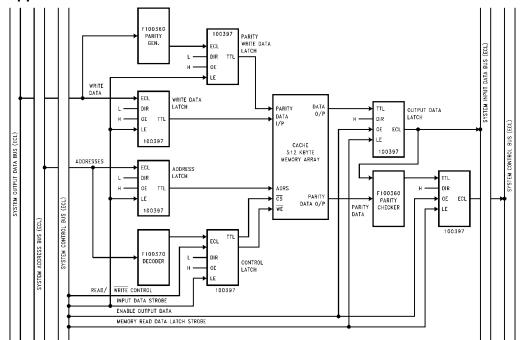
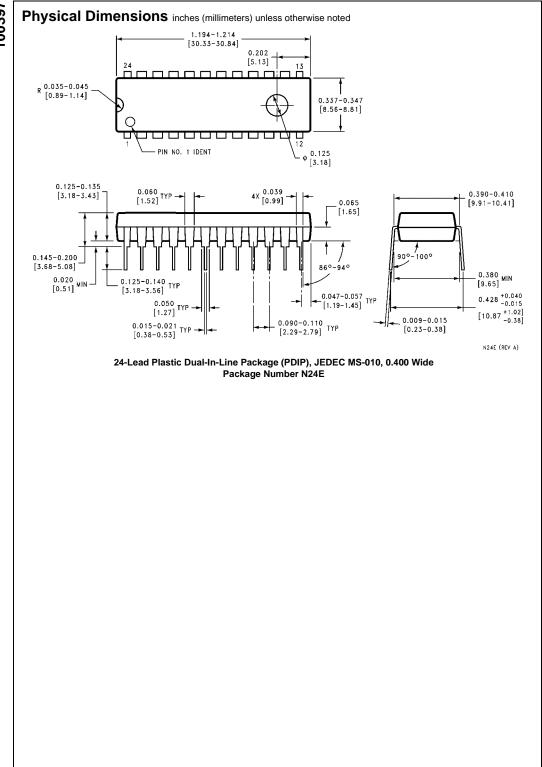
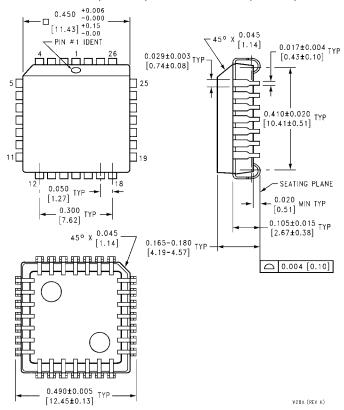


FIGURE 7. Applications Diagram—MOS/TTL SRAM Interface Using 100397 ECL-TTL Latched Translator



#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



28-Lead Plastic Lead Chip Carrier (PLCC), JEDEC MO-047, 0.450 Square Package Number V28A

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